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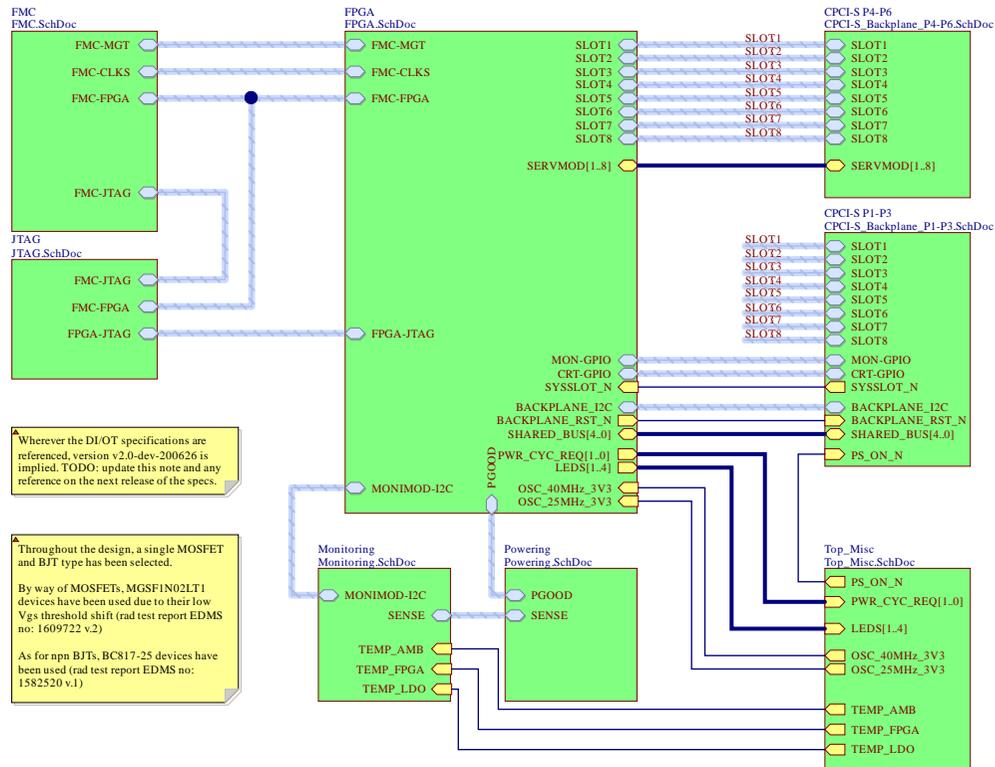
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Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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A Wherever the DI/OT specifications are referenced, version v2.0-dev-200626 is implied. TODO: update this note and any reference on the next release of the specs.

A Throughout the design, a single MOSFET and BJT type has been selected.

By way of MOSFETs, MGSF1N02LT1 devices have been used due to their low Vgs threshold shift (rad test report EDMS no: 1609722 v.2)

As for npn BJTs, BC817-25 devices have been used (rad test report EDMS no: 1582520 v.1)

Project/Equipment		DI/OT	
Document	Designer	C. Gentsos	28/08/2020
BE/CO CERN	Drawn by	C. Gentsos	28/08/2020
	Check by	*	-
	Last Mod.	C. Gentsos	09/10/2020
	File	DIOT-sb-ig1_top.SchDoc	
Print Date	09/10/2020 18:32:26	Sheet	1 of 18
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		EDA-XXXXX-VX-X	18/09/2020 A3

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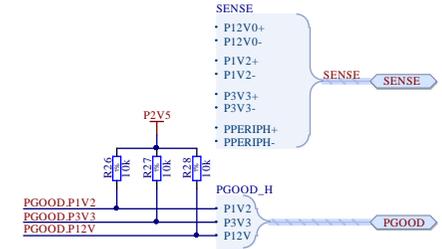
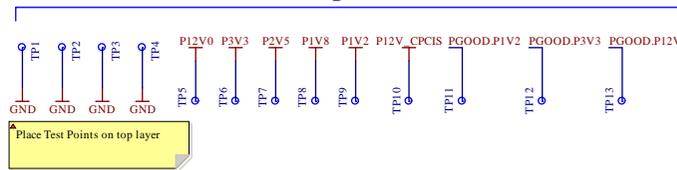
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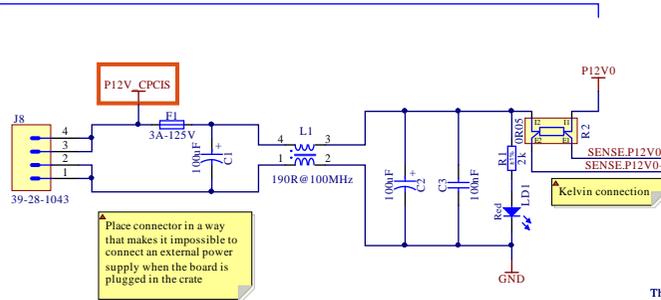
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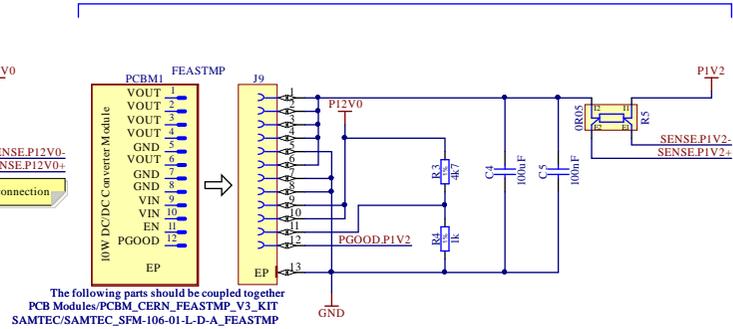
Test points



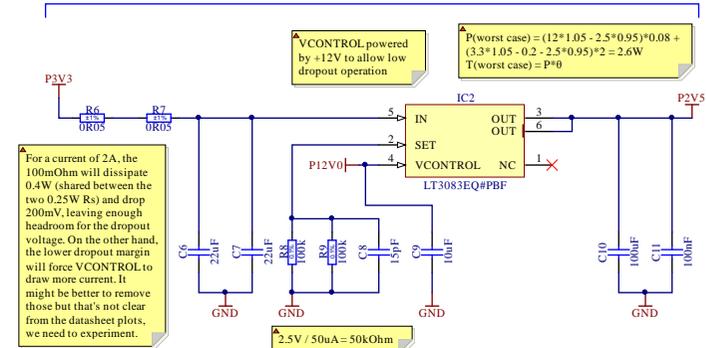
12V0 power cleanup



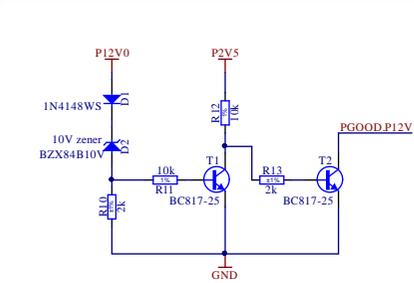
P1V2 power



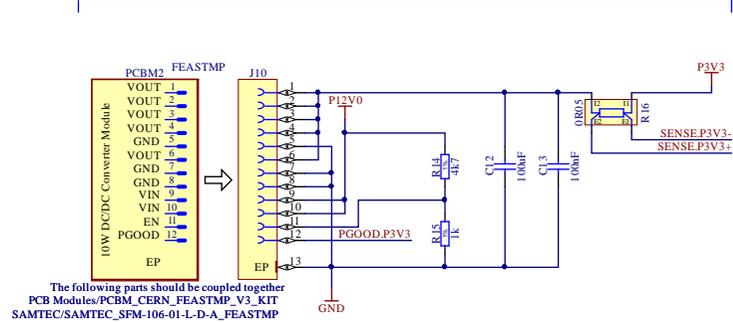
P2V5 power



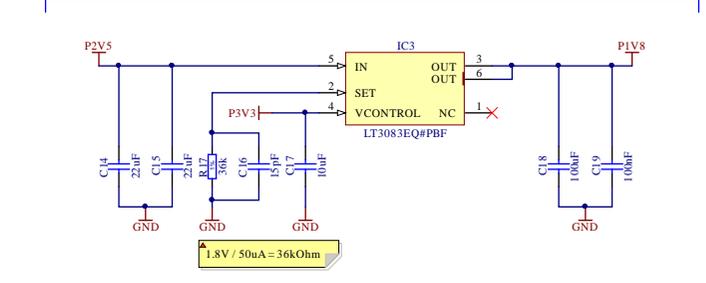
12V brownout detection



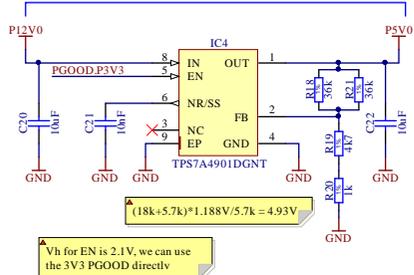
P3V3 power



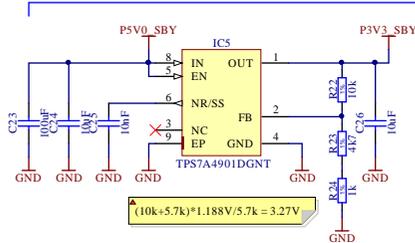
P1V8 power



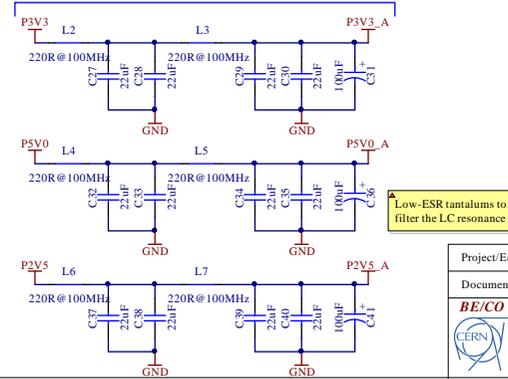
P5V0 power



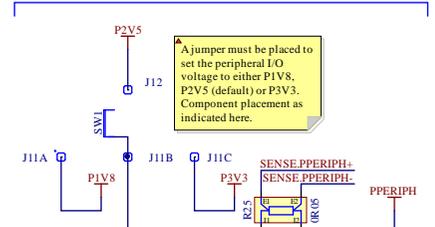
Always-on P3V3 power



Analog power filtering



Peripheral voltage selection



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BE/CO	DI/OT Rad-tol System Board Power	Check by	*
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CERN	European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland	File	Powering_SchDoc
		Print Date	09/10/2020 18:32:27
		Sheet	2 of 18
		EDA-XXXXX-VX-X	A3

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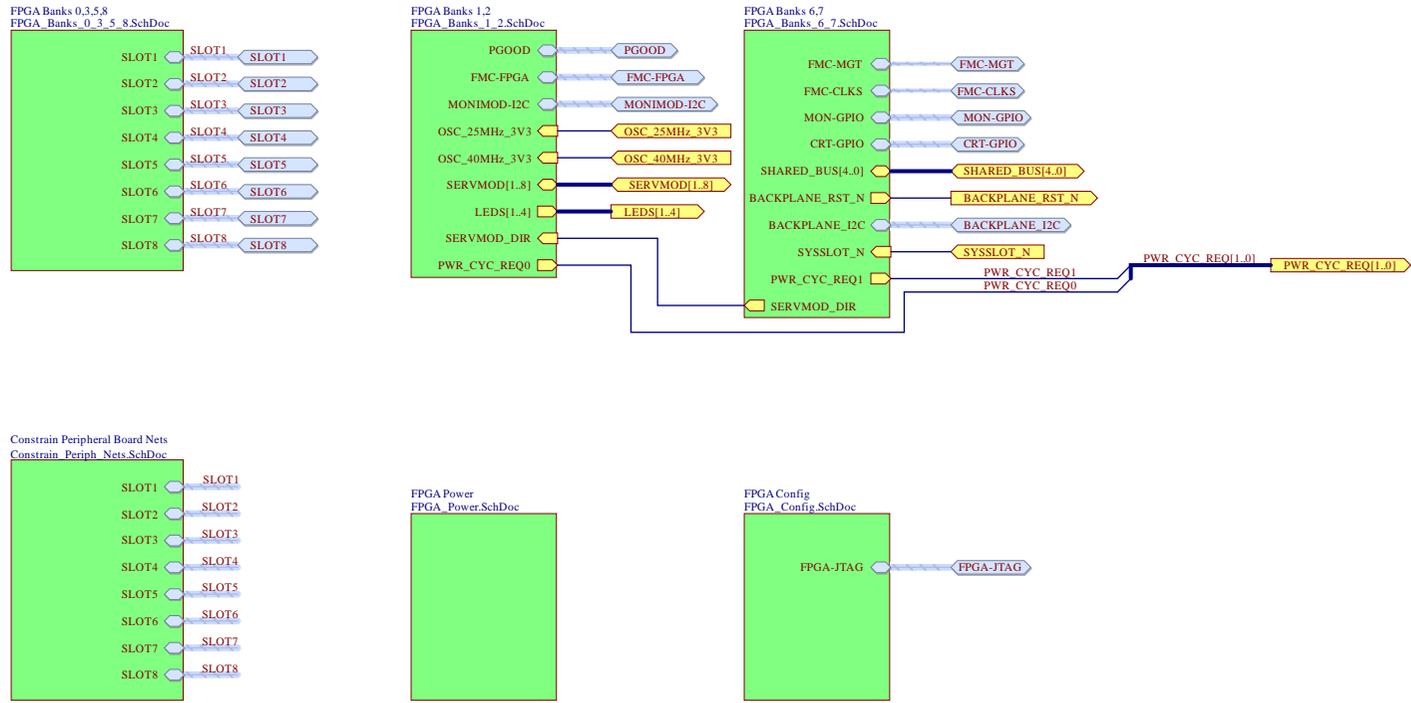
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Project/Equipment		DI/OT	
Document	Designer		C. Gentsos
 DI/OT Rad-tol System Board FPGA Top	Drawn by	C. Gentsos	28/08/2020
	Check by	*	-
	Last Mod.	C. Gentsos	09/10/2020
	File	FPGA_SchDoc	
	Print Date	09/10/2020 18:32:28	Sheet
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		EDA-XXXXX-VX-X	1.000 A3

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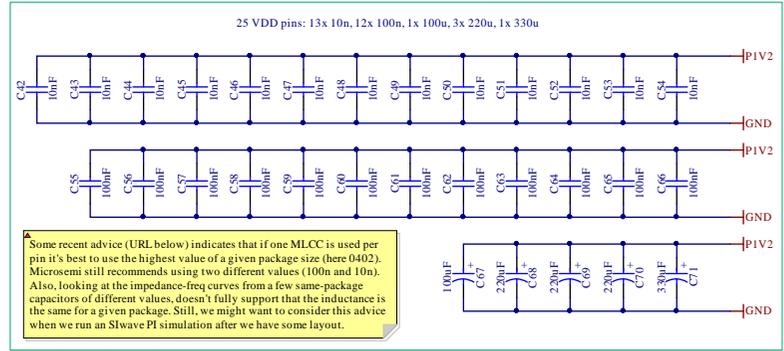
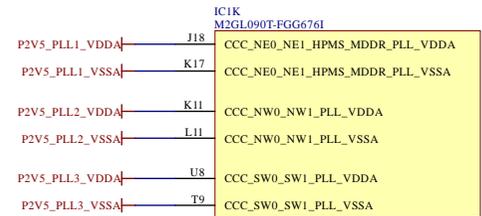
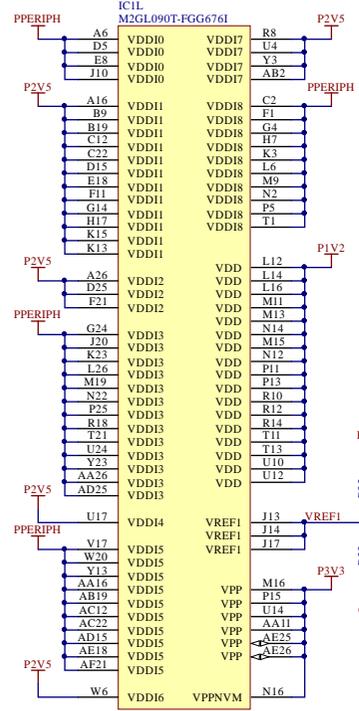
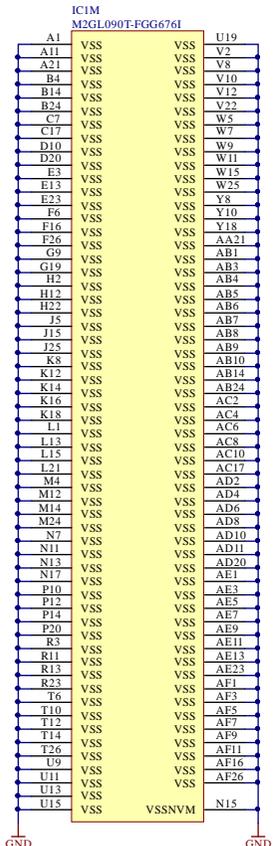
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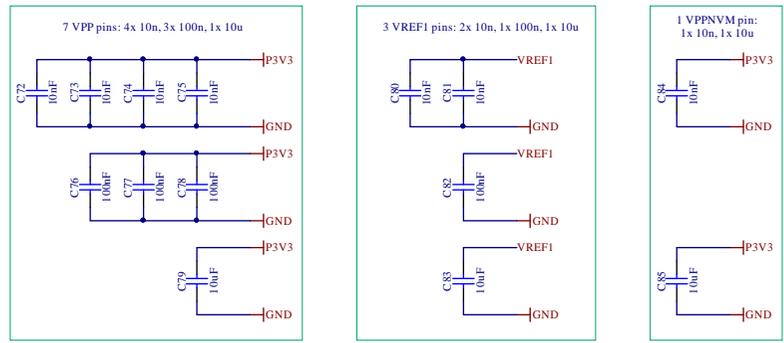
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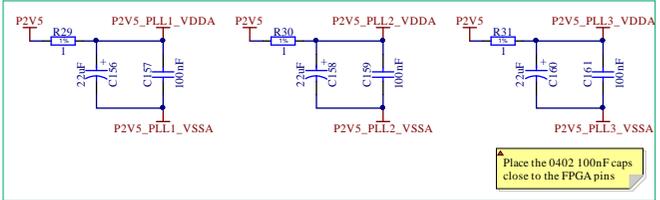
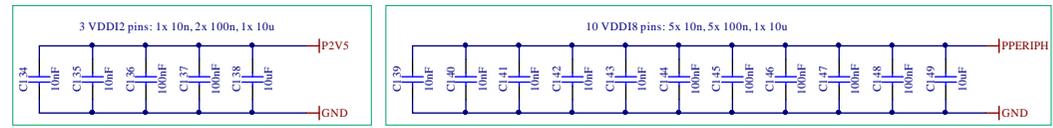
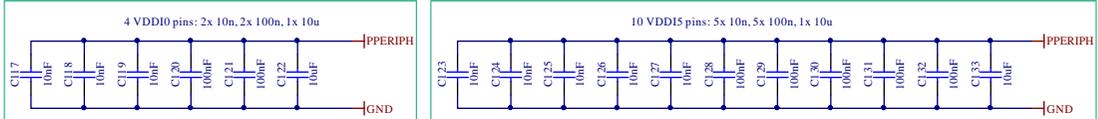
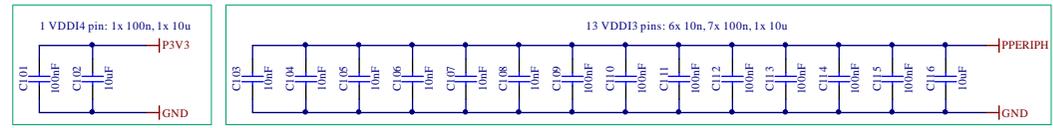
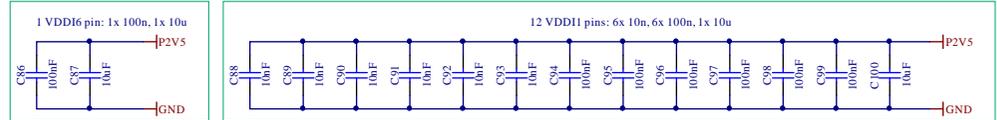
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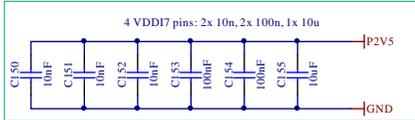
Some recent advice (URL below) indicates that if one MLCC is used per pin it's best to use the highest value of a given package size (here 0402). Microsemi still recommends using two different values (100n and 10n). Also, looking at the impedance-freq curves from a few same-package capacitors of different values, doesn't fully support that the inductance is the same for a given package. Still, we might want to consider this advice when we run an SIwave PI simulation after we have some layout.



PLL power, 2.5V or 3.3V? 2.5V will be smoother due to the LDO so better jitter but is any of the two better for radiation?



Place the 0402 100nF caps close to the FPGA pins



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Document		Drawn by	C. Gentsos
BE/CO	DI/OT Rad-tol System Board FPGA Power	Check by	*
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CERN	European Organization for Nuclear Research CH-1211 Geneva 23 - Switzerland	File	FPGA_PowerSchDoc
		Print Date	09/10/2020 18:32:28
			Sheet 4 of 18
			Tab A3

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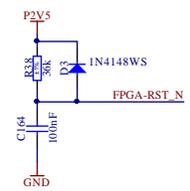
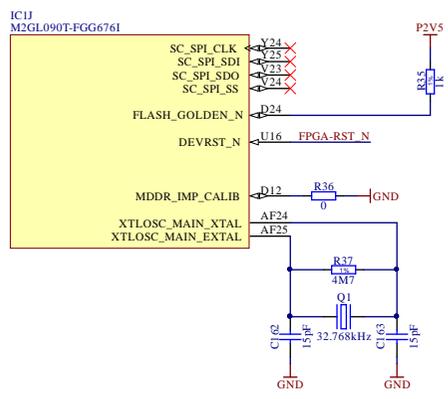
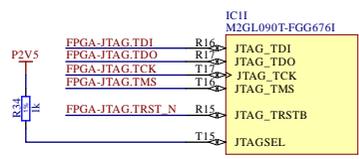
Source location: <https://www.ohwr.org/project/diot-sb-ig1>

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Parts powered by 2.5V



The JTAG and configuration pins are referred to as Bank 4



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Document	Designer		C. Gentsos
 DI/OT Rad-tol System Board FPGA Configuration	Drawn by	C. Gentsos	
	Check by	*	
	Last Mod.	C. Gentsos	
	File	FPGA_Config_SchDoc	
	Print Date	09/10/2020 18:32:29	
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		Sheet	5 of 18
EDA-XXXXX-VX-X		REV	A3

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Banks powered by PPERIPH

Caution on pin-swapping: the S0_P pins are connected to Global I/O pins to be able to drive FPGA clocks and can't be swapped with other peripheral I/Os. Boards 1-3 can drive global buffers directly or use CCCC blocks. Boards 4-6 can drive global buffers directly or through VCCC crossbars; and Boards 7-8 can only reach global buffers through CCCC blocks.

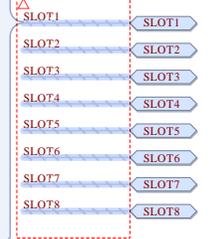
PERIPH_CONN

- LVDS_0_P
- LVDS_0_N
- LVDS_1_P
- LVDS_1_N
- LVDS_2_P
- LVDS_2_N
- LVDS_3_P
- LVDS_3_N
- LVDS_4_P
- LVDS_4_N
- LVDS_5_P
- LVDS_5_N
- LVDS_6_P
- LVDS_6_N
- LVDS_7_P
- LVDS_7_N
- LVDS_8_P
- LVDS_8_N
- LVDS_9_P
- LVDS_9_N
- LVDS_10_P
- LVDS_10_N
- LVDS_11_P
- LVDS_11_N
- LVDS_12_P
- LVDS_12_N
- LVDS_13_P
- LVDS_13_N
- LVDS_14_P
- LVDS_14_N
- LVDS_15_P
- LVDS_15_N
- LVDS_16_P
- LVDS_16_N
- LVDS_17_P
- LVDS_17_N

Intra-diff pair rule. Inter-diff pair rules can be found on a dedicated sheet.

Matched Net Lengths [Tolerance = 5mm]

Class Name: PERIPH_DP



IC1D
M2GL090T-FGG676I

BANK 3

MSIO0NB3	W22	SLOT1LVDS_16_N
MSIO0PB3	W21	SLOT1LVDS_16_P
MSIO1NB3	AA23	SLOT1LVDS_17_N
MSIO1PB3	AA22	SLOT1LVDS_17_P
MSIO2NB3	CC25	SLOT2LVDS_1_N
MSIO2PB3	CC24	SLOT2LVDS_1_P
MSIO3NB3	CC21	SLOT2LVDS_2_N
MSIO3PB3	CC20	SLOT2LVDS_2_P
MSIO4NB3	AD26	SLOT2LVDS_3_N
MSIO4PB3	AD25	SLOT2LVDS_3_P
MSIO5NB3	AD21	SLOT2LVDS_4_N
MSIO5PB3	AD20	SLOT2LVDS_4_P
MSIO6NB3	AD23	SLOT2LVDS_5_P
MSIO6PB3	AD22	SLOT2LVDS_5_N
MSIO7NB3	AA25	SLOT2LVDS_6_N
MSIO7PB3	AA24	SLOT2LVDS_6_P
MSIO8NB3	AB26	SLOT2LVDS_7_N
MSIO8PB3	AB25	SLOT2LVDS_7_P
MSIO9NB3	AD22	SLOT2LVDS_8_N
MSIO9PB3	AD21	SLOT2LVDS_8_P
MSIO10NB3	AD23	SLOT2LVDS_9_N
MSIO10PB3	AD22	SLOT2LVDS_9_P
MSIO11NB3/CCC_NE1_CLKI0	W26	SLOT2LVDS_10_N
MSIO11PB3/CCC_NE1_CLKI0	W25	SLOT2LVDS_10_P
MSIO12NB3/SPL_0_CLK	W26	SLOT2LVDS_11_N
MSIO12PB3/SPL_0_CLK	W25	SLOT2LVDS_11_P
MSIO13NB3/SPL_0_SSD	W26	SLOT2LVDS_12_N
MSIO13PB3/SPL_0_SSD	W25	SLOT2LVDS_12_P
MSIO14NB3	W23	SLOT2LVDS_13_N
MSIO14PB3	W22	SLOT2LVDS_13_P
MSIO15NB3	W23	SLOT2LVDS_14_N
MSIO15PB3	W22	SLOT2LVDS_14_P
MSIO16NB3	W23	SLOT2LVDS_15_N
MSIO16PB3	W22	SLOT2LVDS_15_P
MSIO17NB3	W24	SLOT2LVDS_16_N
MSIO17PB3	W23	SLOT2LVDS_16_P
MSIO18NB3	W24	SLOT2LVDS_17_N
MSIO18PB3	W23	SLOT2LVDS_17_P
MSIO19NB3	W25	SLOT2LVDS_18_N
MSIO19PB3	W24	SLOT2LVDS_18_P
MSIO20NB3/GB13/VCCC_SE1_CLKI	W25	SLOT2LVDS_19_N
MSIO20PB3/GB9/VCCC_SE0_CLKI	W24	SLOT2LVDS_19_P
MSIO21NB3	W26	SLOT2LVDS_20_N
MSIO21PB3	W25	SLOT2LVDS_20_P
MSIO22NB3	W26	SLOT2LVDS_21_N
MSIO22PB3	W25	SLOT2LVDS_21_P
MSIO23NB3	W26	SLOT2LVDS_22_N
MSIO23PB3	W25	SLOT2LVDS_22_P
MSIO24NB3	W27	SLOT2LVDS_23_N
MSIO24PB3	W26	SLOT2LVDS_23_P
MSIO25NB3	W27	SLOT2LVDS_24_N
MSIO25PB3	W26	SLOT2LVDS_24_P
MSIO26NB3	W28	SLOT2LVDS_25_N
MSIO26PB3	W27	SLOT2LVDS_25_P
MSIO27NB3	W28	SLOT2LVDS_26_N
MSIO27PB3	W27	SLOT2LVDS_26_P
MSIO28NB3	W29	SLOT2LVDS_27_N
MSIO28PB3	W28	SLOT2LVDS_27_P
MSIO29NB3	W29	SLOT2LVDS_28_N
MSIO29PB3	W28	SLOT2LVDS_28_P
MSIO30NB3	W30	SLOT2LVDS_29_N
MSIO30PB3	W29	SLOT2LVDS_29_P
MSIO31NB3	W30	SLOT2LVDS_30_N
MSIO31PB3	W29	SLOT2LVDS_30_P
MSIO32NB3	W31	SLOT2LVDS_31_N
MSIO32PB3	W30	SLOT2LVDS_31_P
MSIO33NB3	W31	SLOT2LVDS_32_N
MSIO33PB3	W30	SLOT2LVDS_32_P
MSIO34NB3	W32	SLOT2LVDS_33_N
MSIO34PB3	W31	SLOT2LVDS_33_P
MSIO35NB3	W32	SLOT2LVDS_34_N
MSIO35PB3	W31	SLOT2LVDS_34_P
MSIO36NB3	W33	SLOT2LVDS_35_N
MSIO36PB3	W32	SLOT2LVDS_35_P
MSIO37NB3	W33	SLOT2LVDS_36_N
MSIO37PB3	W32	SLOT2LVDS_36_P
MSIO38NB3	W34	SLOT2LVDS_37_N
MSIO38PB3	W33	SLOT2LVDS_37_P
MSIO39NB3	W34	SLOT2LVDS_38_N
MSIO39PB3	W33	SLOT2LVDS_38_P
MSIO40NB3	W35	SLOT2LVDS_39_N
MSIO40PB3	W34	SLOT2LVDS_39_P
MSIO41NB3	W35	SLOT2LVDS_40_N
MSIO41PB3	W34	SLOT2LVDS_40_P
MSIO42NB3	W36	SLOT2LVDS_41_N
MSIO42PB3	W35	SLOT2LVDS_41_P
MSIO43NB3	W36	SLOT2LVDS_42_N
MSIO43PB3	W35	SLOT2LVDS_42_P
MSIO44NB3	W37	SLOT2LVDS_43_N
MSIO44PB3	W36	SLOT2LVDS_43_P
MSIO45NB3	W37	SLOT2LVDS_44_N
MSIO45PB3	W36	SLOT2LVDS_44_P
MSIO46NB3	W38	SLOT2LVDS_45_N
MSIO46PB3	W37	SLOT2LVDS_45_P
MSIO47NB3	W38	SLOT2LVDS_46_N
MSIO47PB3	W37	SLOT2LVDS_46_P
MSIO48NB3	W39	SLOT2LVDS_47_N
MSIO48PB3	W38	SLOT2LVDS_47_P
MSIO49NB3	W39	SLOT2LVDS_48_N
MSIO49PB3	W38	SLOT2LVDS_48_P
MSIO50NB3	W40	SLOT2LVDS_49_N
MSIO50PB3	W39	SLOT2LVDS_49_P
MSIO51NB3	W40	SLOT2LVDS_50_N
MSIO51PB3	W39	SLOT2LVDS_50_P

IC1E
M2GL090T-FGG676I

BANK 5

MSIO195NB5	W13	SLOT4LVDS_11_N
MSIO195PB5	W12	SLOT4LVDS_11_P
MSIO196NB5/CCC_SW0_CLKI2	W11	SLOT4LVDS_12_N
MSIO196PB5	W10	SLOT4LVDS_12_P
MSIO197NB5/PROBE_B	AD11	SLOT4LVDS_13_N
MSIO197PB5/PROBE_A	AD10	SLOT4LVDS_13_P
MSIO198NB5	Y12	SLOT4LVDS_14_N
MSIO198PB5	AA12	SLOT4LVDS_14_P
MSIO199NB5	AF12	SLOT4LVDS_15_P
MSIO199PB5	AF11	SLOT4LVDS_15_P
MSIO200NB5/GB7/CCC_SW1_CLKI2	AB13	SLOT3LVDS_0_N
MSIO200PB5/GB3/CCC_SW1_CLKI3	AB12	SLOT3LVDS_0_P
MSIO201NB5	AE14	SLOT4LVDS_16_N
MSIO201PB5	AF14	SLOT4LVDS_16_P
MSIO202NB5	AF14	SLOT4LVDS_17_N
MSIO202PB5	AF13	SLOT4LVDS_17_P
MSIO203NB5	AD14	SLOT5LVDS_1_N
MSIO203PB5	AD13	SLOT5LVDS_1_P
MSIO204NB5	AC14	SLOT5LVDS_2_N
MSIO204PB5	AC13	SLOT5LVDS_2_P
MSIO205NB5	AF17	SLOT5LVDS_3_N
MSIO205PB5	AF16	SLOT5LVDS_3_P
MSIO206NB5	AA14	SLOT5LVDS_4_N
MSIO206PB5	AA13	SLOT5LVDS_4_P
MSIO207NB5	AE15	SLOT7LVDS_0_P
MSIO207PB5	AF15	SLOT7LVDS_0_P
MSIO208NB5	Y14	SLOT5LVDS_5_N
MSIO208PB5/CCC_SW1_CLKI3	Y13	SLOT5LVDS_5_P
MSIO209NB5	AE17	SLOT5LVDS_6_N
MSIO209PB5/VCCC_SE0_CLKI	AE16	SLOT5LVDS_6_P
MSIO210NB5	Y17	SLOT5LVDS_6_N
MSIO210PB5/GB11/VCCC_SE0_CLKI	Y16	SLOT5LVDS_6_P
MSIO211NB5	AA17	SLOT5LVDS_6_P
MSIO211PB5	AD17	SLOT6LVDS_0_N
MSIO212NB5	AB15	SLOT5LVDS_7_N
MSIO212PB5/GB15/VCCC_SE1_CLKI	AC15	SLOT5LVDS_7_P
MSIO213NB5	Y15	SLOT5LVDS_8_N
MSIO213PB5/VCCC_SE1_CLKI	Y14	SLOT5LVDS_8_P
MSIO214NB5	AA15	SLOT5LVDS_8_P
MSIO214PB5	AB16	SLOT5LVDS_9_N
MSIO215NB5	AB17	SLOT5LVDS_9_P
MSIO215PB5	AB18	SLOT5LVDS_10_N
MSIO216NB5	V16	SLOT5LVDS_11_N
MSIO216PB5	V15	SLOT5LVDS_11_P
MSIO217NB5	AF20	SLOT5LVDS_12_N
MSIO217PB5	AF19	SLOT5LVDS_12_P
MSIO218NB5	W18	SLOT5LVDS_13_P
MSIO218PB5	AE20	SLOT5LVDS_14_N
MSIO219NB5	AE19	SLOT5LVDS_14_P
MSIO219PB5	W16	SLOT5LVDS_15_N
MSIO220NB5	V16	SLOT5LVDS_15_P
MSIO220PB5	AD19	SLOT5LVDS_16_N
MSIO221NB5	AD18	SLOT5LVDS_16_P
MSIO221PB5	AE21	SLOT5LVDS_17_N
MSIO222NB5	AF22	SLOT5LVDS_17_P
MSIO222PB5	Y19	SLOT6LVDS_1_N
MSIO223NB5	W19	SLOT6LVDS_1_P
MSIO223PB5	AE22	SLOT6LVDS_2_N
MSIO224NB5	AF23	SLOT6LVDS_2_P
MSIO224PB5	Y20	SLOT6LVDS_3_N
MSIO225NB5	Y21	SLOT6LVDS_3_P
MSIO225PB5	AC19	SLOT6LVDS_4_N
MSIO226NB5	AC18	SLOT6LVDS_4_P
MSIO226PB5	V18	SLOT6LVDS_5_N
MSIO227NB5	V19	SLOT6LVDS_5_P
MSIO227PB5	AA19	SLOT6LVDS_6_N
MSIO228NB5	AA18	SLOT6LVDS_6_P
MSIO228PB5	AD23	SLOT6LVDS_7_N
MSIO229NB5	AD22	SLOT6LVDS_7_P
MSIO229PB5	AC20	SLOT6LVDS_8_N
MSIO230NB5	AD21	SLOT6LVDS_8_P
MSIO230PB5	AD24	SLOT6LVDS_9_N
MSIO231NB5	AE24	SLOT6LVDS_9_P
MSIO231PB5	AB21	SLOT6LVDS_10_N
MSIO232NB5	AC21	SLOT6LVDS_10_P
MSIO232PB5	AB22	SLOT6LVDS_11_N
MSIO233NB5	AB22	SLOT6LVDS_12_N
MSIO233PB5	AA22	SLOT6LVDS_12_P
MSIO234NB5	AA20	SLOT6LVDS_13_N
MSIO234PB5	AB20	SLOT6LVDS_13_P

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BANK 8

MSIO126NB8	G7	SLOT6LVDS_14_N
MSIO126PB8	H8	SLOT6LVDS_14_P
MSIO127NB8	H6	SLOT6LVDS_15_N
MSIO127PB8	H5	SLOT6LVDS_15_P
MSIO128NB8	H7	SLOT6LVDS_16_N
MSIO128PB8	H6	SLOT6LVDS_16_P
MSIO129NB8	G6	SLOT6LVDS_17_N
MSIO129PB8	G5	SLOT6LVDS_17_P
MSIO129NB8	H5	SLOT7LVDS_1_N
MSIO129PB8	H4	SLOT7LVDS_1_P
MSIO130NB8	H5	SLOT7LVDS_2_N
MSIO130PB8	H4	SLOT7LVDS_2_P
MSIO131NB8	H4	SLOT7LVDS_3_N
MSIO131PB8	H3	SLOT7LVDS_3_P
MSIO132NB8	H5	SLOT7LVDS_4_N
MSIO132PB8	H4	SLOT7LVDS_4_P
MSIO133NB8	H3	SLOT7LVDS_5_N
MSIO133PB8	H2	SLOT7LVDS_5_P
MSIO134NB8	H3	SLOT7LVDS_6_N
MSIO134PB8	H2	SLOT7LVDS_6_P
MSIO135NB8	H4	SLOT7LVDS_7_N
MSIO135PB8	H3	SLOT7LVDS_7_P
MSIO136NB8	H3	SLOT7LVDS_8_N
MSIO136PB8	H2	SLOT7LVDS_8_P
MSIO137NB8	H8	SLOT7LVDS_9_N
MSIO137PB8	H7	SLOT7LVDS_9_P
MSIO138NB8	A3	SLOT7LVDS_10_N
MSIO138PB8	A2	SLOT7LVDS_10_P
MSIO139NB8	H9	SLOT7LVDS_11_N
MSIO139PB8	H8	SLOT7LVDS_11_P
MSIO140NB8	H9	SLOT7LVDS_12_N
MSIO140PB8	H8	SLOT7LVDS_12_P
MSIO141NB8	H9	SLOT7LVDS_13_N
MSIO141PB8	H8	SLOT7LVDS_13_P
MSIO142NB8	H9	SLOT7LVDS_14_N
MSIO142PB8	H8	SLOT7LVDS_14_P
MSIO143NB8	H9	SLOT7LVDS_15_N
MSIO143PB8	H8	SLOT7LVDS_15_P
MSIO144NB8	H9	SLOT7LVDS_16_N
MSIO144PB8	H8	SLOT7LVDS_16_P
MSIO145NB8	H9	SLOT7LVDS_17_N
MSIO145PB8	H8	SLOT7LVDS_17_P
MSIO146NB8	H9	SLOT8LVDS_1_N
MSIO146PB8	H8	SLOT8LVDS_1_P
MSIO147NB8	H9	SLOT8LVDS_2_N
MSIO147PB8	H8	SLOT8LVDS_2_P
MSIO148NB8	H9	SLOT8LVDS_3_N
MSIO148PB8	H8	SLOT8LVDS_3_P
MSIO149NB8	H9	SLOT8LVDS_4_N
MSIO149PB8	H8	SLOT8LVDS_4_P
MSIO150NB8	H9	SLOT8LVDS_5_N
MSIO150PB8	H8	SLOT8LVDS_5_P
MSIO151NB8	H9	SLOT8LVDS_6_N
MSIO151PB8	H8	SLOT8LVDS_6_P
MSIO152NB8	H9	SLOT8LVDS_7_N
MSIO152PB8	H8	SLOT8LVDS_7_P
MSIO153NB8	H9	SLOT8LVDS_8_N
MSIO153PB8	H8	SLOT8LVDS_8_P
MSIO154NB8	H9	SLOT8LVDS_9_N
MSIO154PB8	H8	SLOT8LVDS_9_P
MSIO155NB8	H9	SLOT8LVDS_10_N
MSIO155PB8	H8	SLOT8LVDS_10_P
MSIO156NB8/GB6/CCC_NW1_CLKI0	H9	SLOT8LVDS_11_N
MSIO156PB8/GB6/CCC_NW1_CLKI0	H8	SLOT8LVDS_11_P
MSIO157NB8/GB2/CCC_NW0_CLKI1	H9	SLOT8LVDS_12_N
MSIO157PB8/GB2/CCC_NW0_CLKI1	H8	SLOT8LVDS_12_P
MSIO158NB8	H9	SLOT8LVDS_13_N
MSIO158PB8	H8	SLOT8LVDS_13_P
MSIO159NB8/CCC_NW1_CLKI0	H9	SLOT8LVDS_14_N
MSIO159PB8/CCC_NW1_CLKI0	H8	SLOT8LVDS_14_P
MSIO160NB8	H9	SLOT8LVDS_15_N
MSIO160PB8	H8	SLOT8LVDS_15_P
MSIO161NB8	H9	SLOT8LVDS_16_N
MSIO161PB8	H8	SLOT8LVDS_16_P
MSIO162NB8	H9	SLOT8LVDS_17_N
MSIO162PB8	H8	SLOT8LVDS_17_P
MSIO163NB8	H9	SLOT8LVDS_18_N
MSIO163PB8	H8	SLOT8LVDS_18_P
MSIO164NB8	H9	SLOT8LVDS_19_N
MSIO164PB8	H8	SLOT8LVDS_19_P
MSIO165NB8	H9	SLOT8LVDS_20_N
MSIO165PB8	H8	SLOT8LVDS_20_P
MSIO166NB8	H9	SLOT8LVDS_21_N
MSIO166PB8	H8	SLOT8LVDS_21_P
MSIO167NB8	H9	SLOT8LVDS_22_N
MSIO167PB8	H8	SLOT8LVDS_22_P
MSIO168NB8	H9	SLOT8LVDS_23_N
MSIO168PB8	H8	SLOT8LVDS_23_P
MSIO169NB8	H9	SLOT8LVDS_24_N
MSIO169PB8	H8	SLOT8LVDS_24_P
MSIO170NB8	H9	SLOT8LVDS_25_N
MSIO170PB8	H8	SLOT8LVDS_25_P
MSIO171NB8	H9	SLOT8LVDS_26_N
MSIO171PB8	H8	SLOT8LVDS_26_P
MSIO172NB8	H9	SLOT8LVDS_27_N
MSIO172PB8	H8	SLOT8LVDS_27_P
MSIO173NB8	H9	SLOT8LVDS_28_N
MSIO173PB8	H8	SLOT8LVDS_28_P

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BANK 0

MSIO11NB0	J12	SLOT1LVDS_1_N
MSIO11PB0	J11	SLOT1LVDS_1_P
MSIO112NB0	A9	SLOT1LVDS_2_N
MSIO112PB0	A8	SLOT1LVDS_2_P
MSIO113NB0	J10	SLOT1LVDS_3_N
MSIO113PB0	B8	SLOT1LVDS_4_N
MSIO114NB0	A7	SLOT1LVDS_4_P
MSIO114PB0	H10	SLOT1LVDS_5_N
MSIO115NB0	H9	SLOT1LVDS_5_P
MSIO116NB0	J8	SLOT1LVDS_6_N
MSIO116PB0	J8	SLOT1LVDS_6_P
MSIO117NB0	J10	SLOT1LVDS_7_N
MSIO117PB0	H9	SLOT1LVDS_7_P
MSIO118NB0</		

Banks powered by 2.5V

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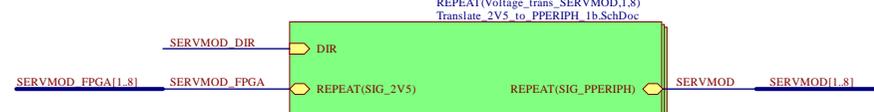
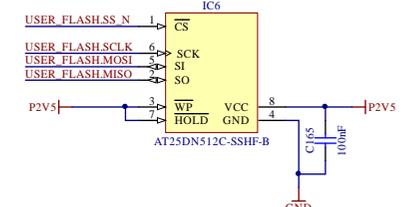
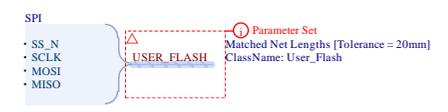
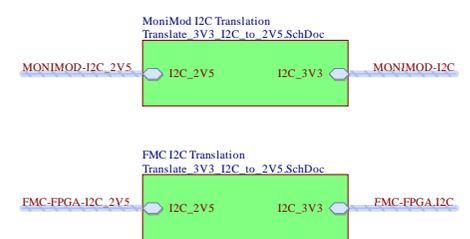
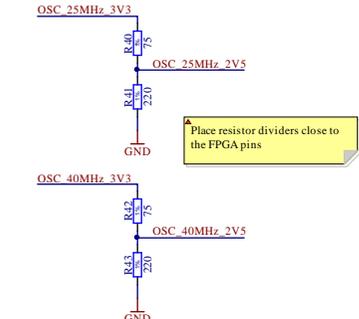
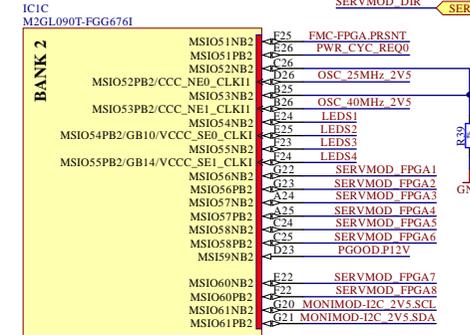
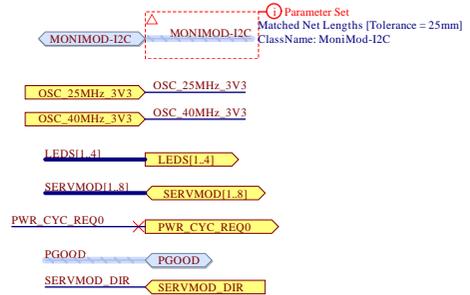
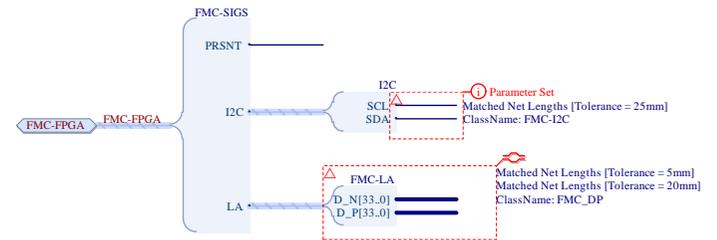
Source location: https://www.ohw.org/project/di-ot-sb-ig1

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Careful with pin swapping: the P nets of the differential pairs 0, 1, 17 and 18 are connected to clock-capable pins and can't be swapped with the other I/Os.

IC1B M2GL090T-FGG6761

BANK 1		BANK 2	
DDRIO62NB1/MDDR_ADDR15	C23	FMC-FPGA.L.A.D_N14	
DDRIO62PB1/MDDR_ADDR15	C22	FMC-FPGA.L.A.D_P14	
DDRIO63NB1/MDDR_ADDR16	C23	FMC-FPGA.L.A.D_N15	
DDRIO63PB1/MDDR_ADDR16	C23	FMC-FPGA.L.A.D_P15	
DDRIO64NB1/MDDR_ADDR11	C21	FMC-FPGA.L.A.D_N2	
DDRIO64PB1/MDDR_ADDR10	C20	FMC-FPGA.L.A.D_N3	
DDRIO65NB1/MDDR_ADDR9	C20	FMC-FPGA.L.A.D_P3	
DDRIO65PB1/MDDR_ADDR8	C22	FMC-FPGA.L.A.D_N4	
DDRIO66NB1/MDDR_ADDR7	C22	FMC-FPGA.L.A.D_P4	
DDRIO66PB1/MDDR_ODT	C18	FMC-FPGA.L.A.D_N5	
DDRIO67NB1/MDDR_ADDR6	C18	FMC-FPGA.L.A.D_P5	
DDRIO67PB1/MDDR_ADDR5	C21	FMC-FPGA.L.A.D_N6	
DDRIO68NB1/MDDR_ADDR4	C21	FMC-FPGA.L.A.D_P6	
DDRIO68PB1/MDDR_ADDR3	C19	FMC-FPGA.L.A.D_N7	
DDRIO69NB1/MDDR_ADDR2	C19	FMC-FPGA.L.A.D_P7	
DDRIO70NB1/MDDR_ADDR0	C18	FMC-FPGA.L.A.D_N8	
DDRIO70PB1/MDDR_BA2	C17	FMC-FPGA.L.A.D_P8	
DDRIO71NB1/MDDR_BA1	C20	FMC-FPGA.L.A.D_N9	
DDRIO71PB1/MDDR_BA0	C20	FMC-FPGA.L.A.D_P9	
DDRIO72NB1/MDDR_CLK_N	C20	FMC-FPGA.L.A.D_N10	
DDRIO72PB1/MDDR_CLK_N	C19	FMC-FPGA.L.A.D_P10	
DDRIO73NB1/MDDR_CAS_N	C19	FMC-FPGA.L.A.D_N11	
DDRIO73PB1/MDDR_RESET_N	C18	FMC-FPGA.L.A.D_P11	
DDRIO74NB1/MDDR_CS_N	C17	FMC-FPGA.L.A.D_N12	
DDRIO74PB1/MDDR_CKE	C17	FMC-FPGA.L.A.D_P12	
DDRIO75NB1/MDDR_WE_N	C16	FMC-FPGA.L.A.D_N13	
DDRIO75PB1/MDDR_RAS_N	C16	FMC-FPGA.L.A.D_P13	
DDRIO76NB1/MDDR_DQ15	C19	FMC-FPGA.L.A.D_N1	
DDRIO76PB1/CCC_NE1_CLK13/MDDR_DQ14	C18	FMC-FPGA.L.A.D_P1	
DDRIO77NB1/MDDR_DQ13	C18	FMC-FPGA.L.A.D_N12	
DDRIO77PB1/MDDR_DQ12/GB12/CCC_NE1_CLK12	C15	FMC-FPGA.L.A.D_P0	
DDRIO78NB1/MDDR_DM_RDQS1	C16	FMC-FPGA.L.A.D_N16	
DDRIO78PB1/MDDR_TMATCH_0_IB1	C16	FMC-FPGA.L.A.D_P16	
DDRIO79NB1/MDDR_DQS1_L	C17	FMC-FPGA.L.A.D_N17	
DDRIO79PB1/MDDR_DQS1/GB8/CCC_NE0_CLK13	C17	FMC-FPGA.L.A.D_P17	
DDRIO80NB1/MDDR_DQ11	C17	FMC-FPGA.L.A.D_N18	
DDRIO80PB1/MDDR_DQ10/CCC_NE0_CLK12	C16	FMC-FPGA.L.A.D_P18	
DDRIO81NB1/MDDR_DQ9	C16	FMC-FPGA.L.A.D_N19	
DDRIO81PB1/MDDR_DQ8	C16	FMC-FPGA.L.A.D_P19	
DDRIO82NB1/MDDR_TMATCH_0_OUT	C15	FMC-FPGA.L.A.D_N20	
DDRIO82PB1/MDDR_DQ7	C15	FMC-FPGA.L.A.D_P20	
DDRIO83NB1/MDDR_DQ6	C16	FMC-FPGA.L.A.D_N21	
DDRIO83PB1/MDDR_DQ5	C15	FMC-FPGA.L.A.D_P21	
DDRIO84NB1/MDDR_DQ4	C14	FMC-FPGA.L.A.D_N22	
DDRIO84PB1/MDDR_DM_RDQS0	C14	FMC-FPGA.L.A.D_P22	
DDRIO85NB1/MDDR_DQS0_N	C15	FMC-FPGA.L.A.D_N23	
DDRIO85PB1/MDDR_DQS0	C14	FMC-FPGA.L.A.D_P23	
DDRIO86NB1/MDDR_DQ3	C14	FMC-FPGA.L.A.D_N24	
DDRIO86PB1/MDDR_DQ2	C14	FMC-FPGA.L.A.D_P24	
DDRIO87NB1/MDDR_DQ1	C14	FMC-FPGA.L.A.D_N25	
DDRIO87PB1/MDDR_DQ0	C13	FMC-FPGA.L.A.D_P25	
DDRIO88NB1	C13	FMC-FPGA.L.A.D_N26	
DDRIO88PB1/CCC_NW1_CLK13	C13	FMC-FPGA.L.A.D_P26	
DDRIO89NB1/MDDR_DQ_ECC0	C13	FMC-FPGA.L.A.D_N27	
DDRIO89PB1/MDDR_DQ_ECC1	C13	FMC-FPGA.L.A.D_P27	
DDRIO90NB1/MDDR_DM_RDQS_ECC	C13	FMC-FPGA.L.A.D_N28	
DDRIO90PB1/MDDR_TMATCH_ECC_IN	C12	FMC-FPGA.L.A.D_P28	
DDRIO91NB1/MDDR_DQS_ECC_N	C12	FMC-FPGA.L.A.D_N29	
DDRIO91PB1/MDDR_DQS_ECC	C12	FMC-FPGA.L.A.D_P29	
DDRIO92NB1/GB4/CCC_NW1_CLK12	C12	FMC-FPGA.L.A.D_N30	
DDRIO92PB1/GB0/CCC_NW0_CLK13	C12	FMC-FPGA.L.A.D_P30	
DDRIO93NB1/CCC_NW0_CLK12	C11	FMC-FPGA.L.A.D_N31	
DDRIO93PB1/MDDR_TMATCH_ECC_OUT	C11	FMC-FPGA.L.A.D_P31	
DDRIO94NB1	C11	FMC-FPGA.L.A.D_N32	
DDRIO94PB1	C11	FMC-FPGA.L.A.D_P32	
DDRIO95NB1	C11	FMC-FPGA.L.A.D_N33	
DDRIO95PB1	C10	FMC-FPGA.L.A.D_P33	
DDRIO96NB1	C10	FMC-FPGA-12C_2V5_SCL	
DDRIO96PB1	C10	FMC-FPGA-12C_2V5_SDA	
DDRIO97NB1	C12	USER_FLASH_SS_N	
DDRIO97PB1	C11	USER_FLASH_SCLK	
DDRIO98NB1	C9	USER_FLASH_MOSI	
DDRIO98PB1	C10	USER_FLASH_MISO	
DDRIO99NB1	C10	PGOOD_P12V	
DDRIO99PB1	C9	PGOOD_P3V3	



We change SERVMOD direction in pairs

Project/Equipment		DI/OT	
Document	BE/CO		
		DI/OT Rad-tol System Board FPGA I/O Banks B1, B2	
Designer	C. Gentsos	28/08/2020	
Drawn by	C. Gentsos	28/08/2020	
Check by	*		
Last Mod.	C. Gentsos	09/10/2020	
File	FPGA_Banks_1_2_SchDoc		
Print Date	09/10/2020 18:32:31	Sheet	7 of 18
European Organization for Nuclear Research		CH-1211 Genève 23 - Switzerland	
EDA-XXXXX-VX-X		A3	

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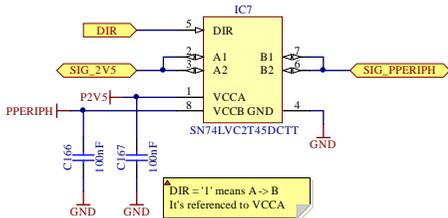
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Maybe that's nit-picking but according to the datasheet, VCCB must be ramped-up with or after VCCA. If VCCB is set to 3V3 its ramp-up will come just slightly ahead of VCCA but not by much.



DIR = '1' means A -> B
It's referenced to VCCA

Project/Equipment		DI/OT		
Document	DI/OT Rad-tol System Board		Designer	C. Gentsos
	Voltage Translators		Drawn by	C. Gentsos
			Check by	*
			Last Mod.	C. Gentsos
			File	Translate_2V5_to_PPERIPH_1b.SchDoc
			Print Date	09/10/2020 18:32:32
			Sheet	8 of 18
 European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland				DATE A3

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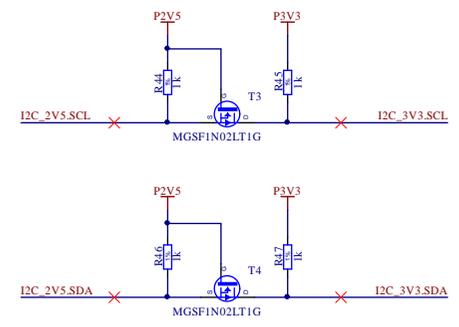
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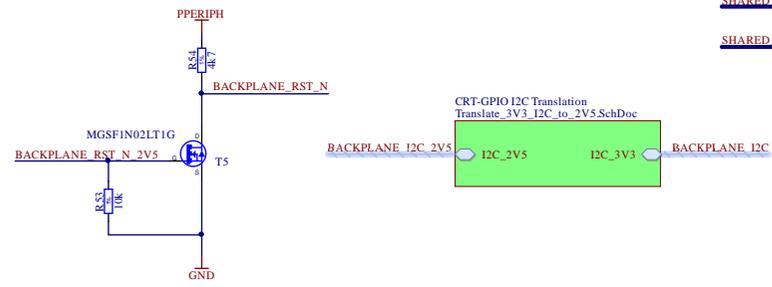
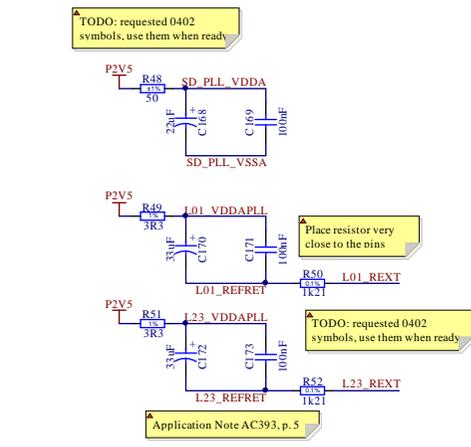
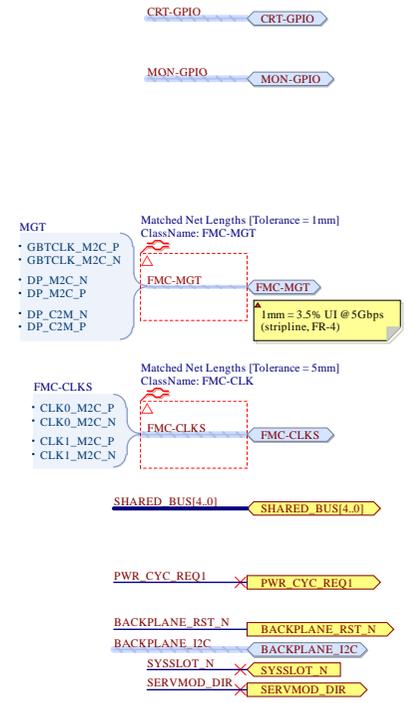
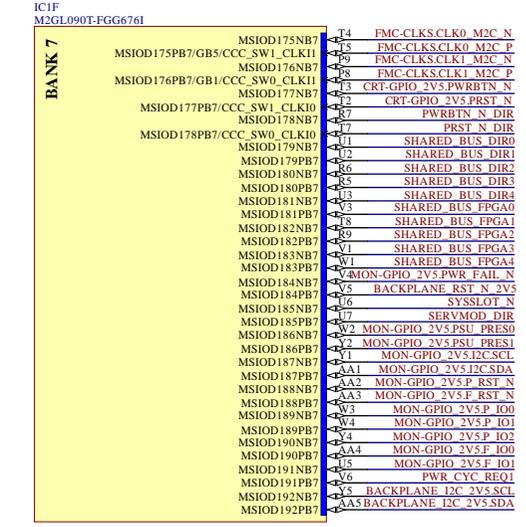
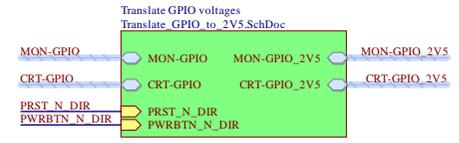
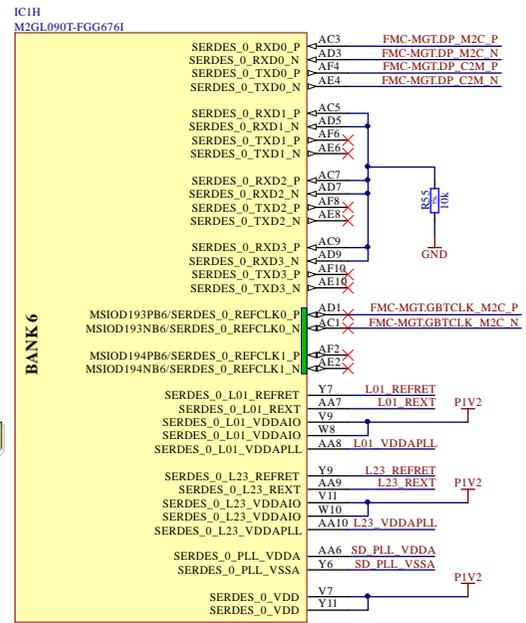
Project/Equipment		DI/OT	
Document		Designer	C. Gentsos
BE/CO		Drawn by	C. Gentsos
CERN		Check by	*
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		Last Mod.	C. Gentsos
		File	Translate_3V3_I2C_to_2V5_SchDoc
		Print Date	09/10/2020 18:32:32
		Sheet	9 of 18
		DATE	A3
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DI/OT Rad-tol System Board
I2C Voltage Translators

EDA-XXXXX-VX-X

Banks powered by 2.5V

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Project/Equipment	DI/OT	Designer	C. Gentsos	28/08/2020
Document		Drawn by	C. Gentsos	
		Check by	*	
		Last Mod.	C. Gentsos	09/10/2020
		File	FPGA_Banks_6_7.SchDoc	
		Print Date	09/10/2020 18:32:32	Sheet 10 of 18
				Rev A3

BE/CO
 CERN
**DI/OT Rad-tol System Board
 FPGA I/O Banks B6, B7**
 European Organization for Nuclear Research
 CH-1211 Geneva 23 - Switzerland
 EDA-XXXXX-VX-X

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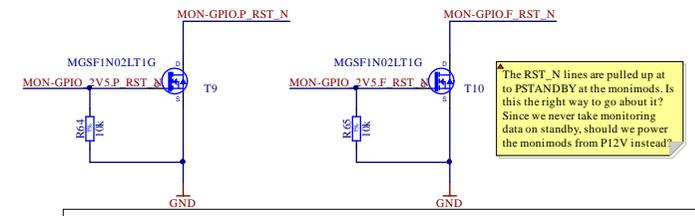
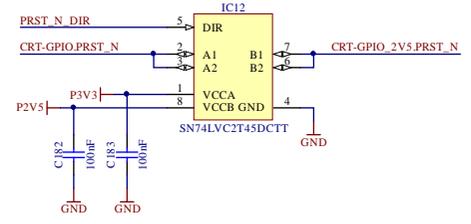
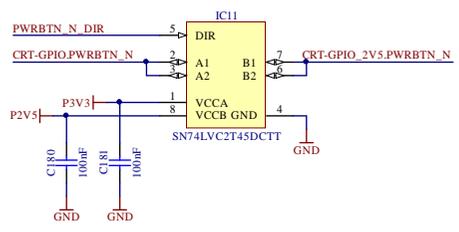
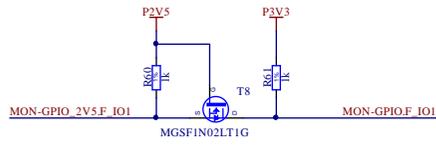
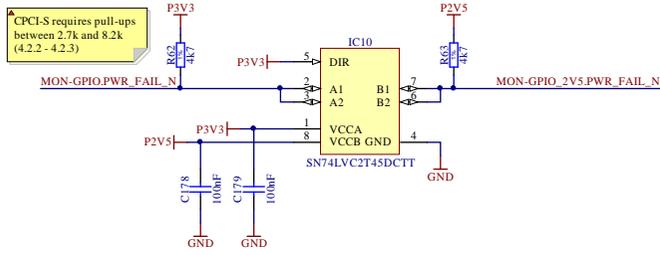
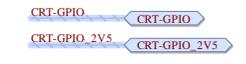
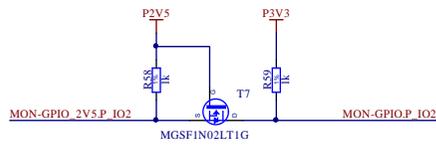
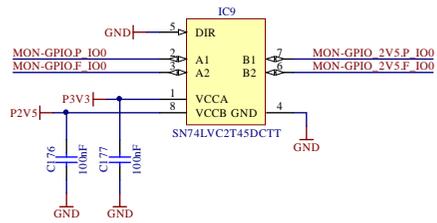
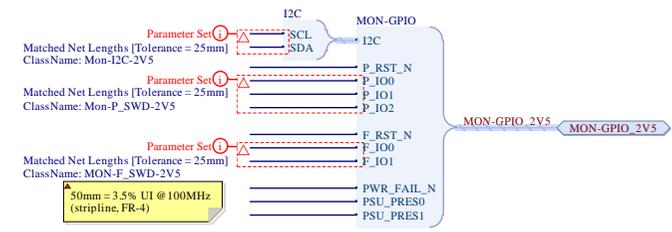
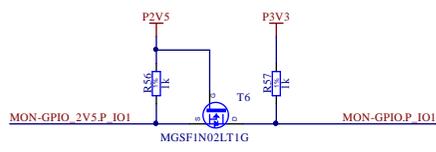
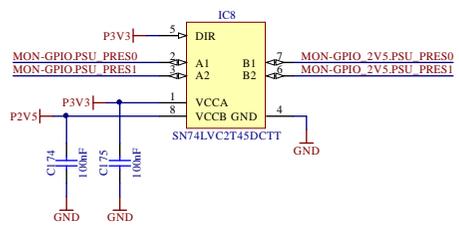
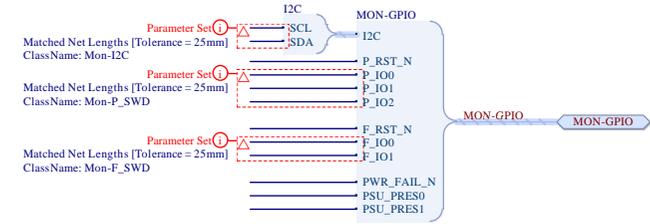
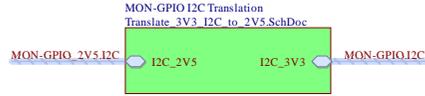
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Project/Equipment: DI/OT		Designer: C. Gentsos	
Document: BE/CO		Drawn by: C. Gentsos	
CERN		Check by: *	
DI/OT Rad-tol System Board GPIO Voltage Translators		Last Mod: C. Gentsos	
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		File: Translate_GPIO_to_2V5.SchDoc	
		Print Date: 09/10/2020 18:32:33	
		Sheet: 11 of 18	
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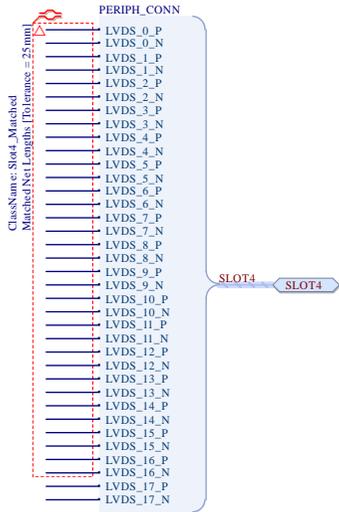
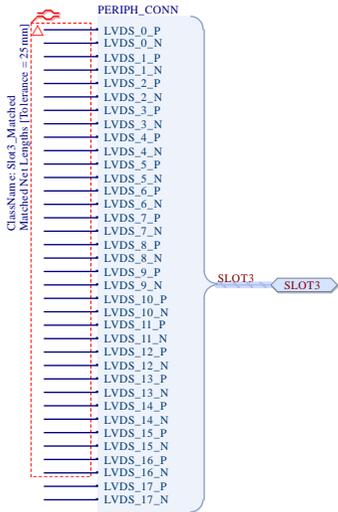
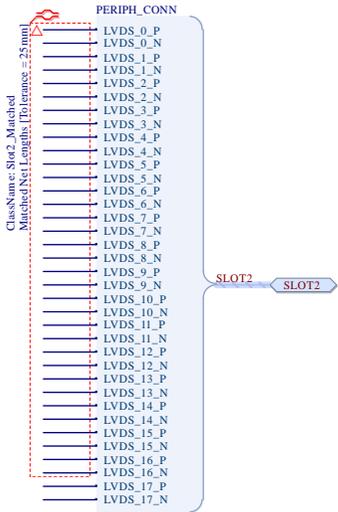
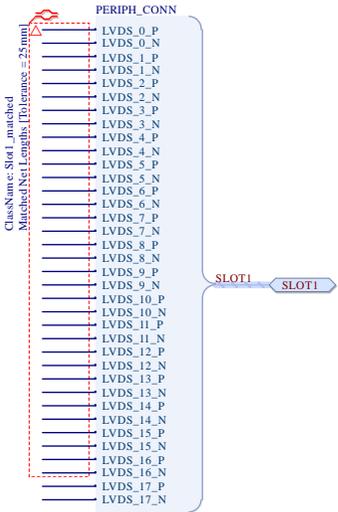
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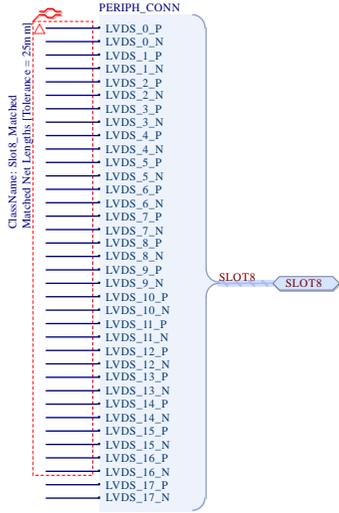
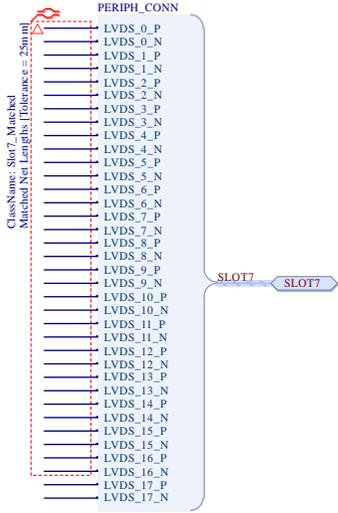
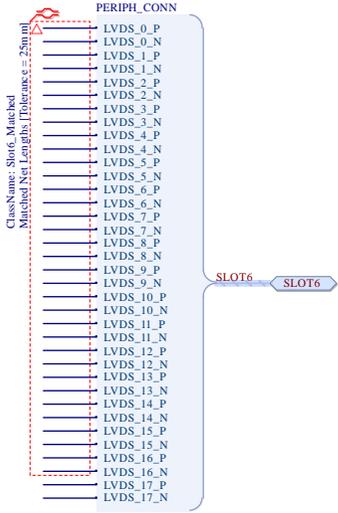
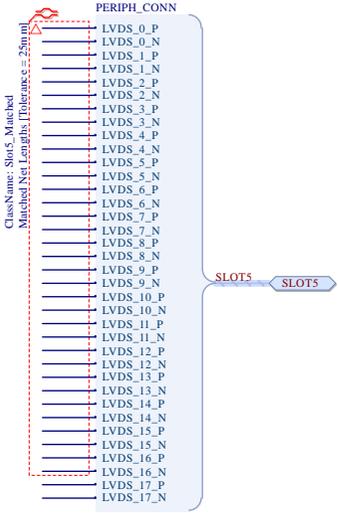
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The diff. pairs that go to each peripheral board are length-matched, excluding the clock-capable pair

The clock-capable pairs are length-matched between the different peripheral boards, instead



- SLOT1 LVDS 17_P
- SLOT1 LVDS 17_N
- SLOT2 LVDS 17_P
- SLOT2 LVDS 17_N
- SLOT3 LVDS 17_P
- SLOT3 LVDS 17_N
- SLOT4 LVDS 17_P
- SLOT4 LVDS 17_N
- SLOT5 LVDS 17_P
- SLOT5 LVDS 17_N
- SLOT6 LVDS 17_P
- SLOT6 LVDS 17_N
- SLOT7 LVDS 17_P
- SLOT7 LVDS 17_N
- SLOT8 LVDS 17_P
- SLOT8 LVDS 17_N



Project/Equipment		DI/OT					
Document	Designer		C. Gentsos				
	Drawn by		C. Gentsos				
	Check by		*				
	Last Mod.		C. Gentsos				
	File		Constrain_Periph_Nets.SchDoc				
Print Date	09/10/2020 18:32:33	Sheet	12 of 18				
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		EDA-XXXXX-VX-X	<table border="1"> <tr> <td>Rev</td> <td>*</td> </tr> <tr> <td>A3</td> <td></td> </tr> </table>	Rev	*	A3	
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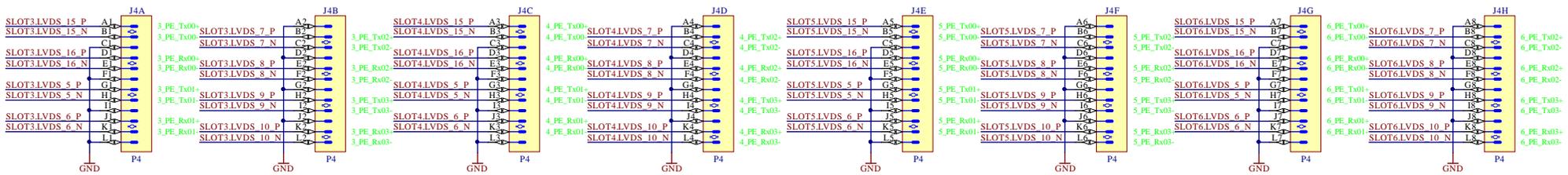
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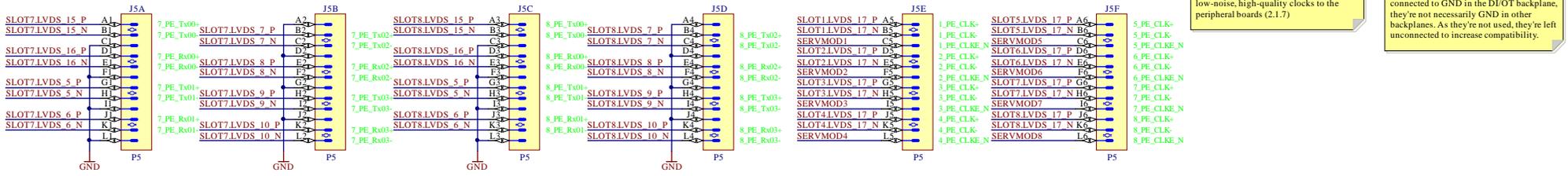
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P4 Connector



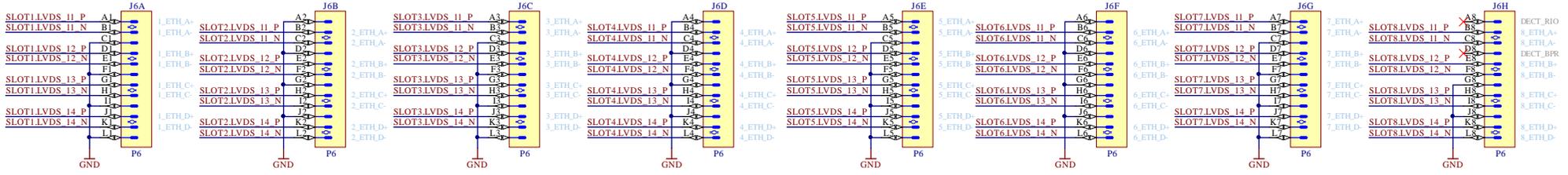
P5 Connector



1. PE_CLK diff pairs will provide low-noise, high-quality clocks to the peripheral boards (2.1.7)

The DECT_RIO and DECT_BPR pins are connected to GND in the DI/OT backplane, they're not necessarily GND in other backplanes. As they're not used, they're left unconnected to increase compatibility.

P6 Connector



Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
CERN		Check by +	
		Last Mod. C. Gentsos	
		File CPCL-S_Backplane_P4-P6_SchDoc	
		Print Date 09/10/2020 18:32:35	
		Sheet 14 of 18	
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		CH-1211 Genève 23 - Switzerland	
		A3	

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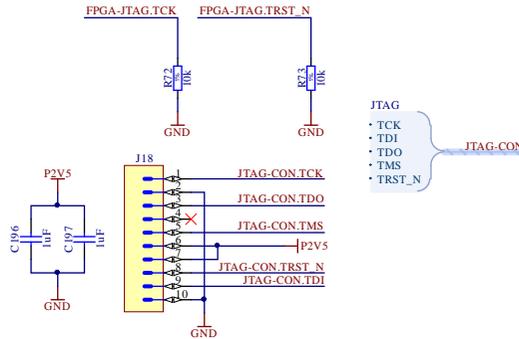
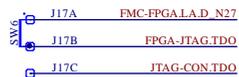
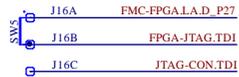
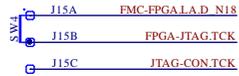
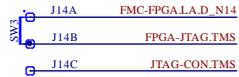
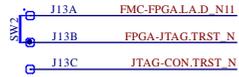
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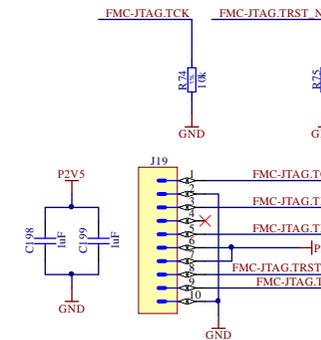
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- JTAG
- TCK
 - TDI
 - TDO
 - TMS
 - TRST_N
- JTAG-CON



Don't confuse this with the nanoFIP JTAG, this is just to provide an easily accessible JTAG connector to program the FMC card

Project/Equipment		DI/OT	
Document		Designer C. Gentsos	
BE/CO		Drawn by C. Gentsos	
CERN		Check by *	
		Last Mod. C. Gentsos	
		File JTAG.SchDoc	
		Print Date 09/10/2020 18:32:37	
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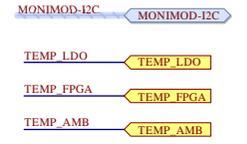
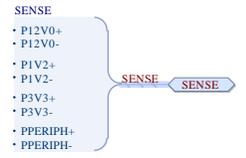
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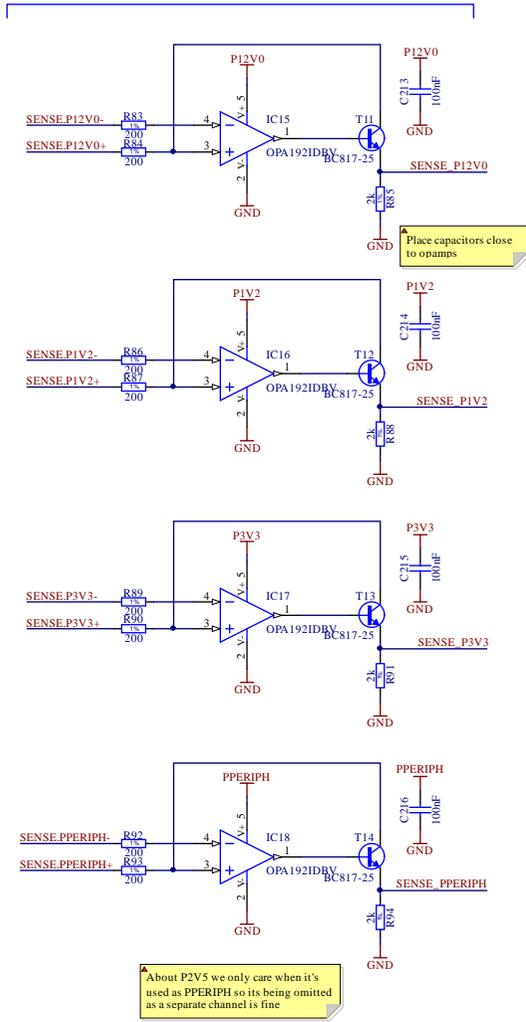
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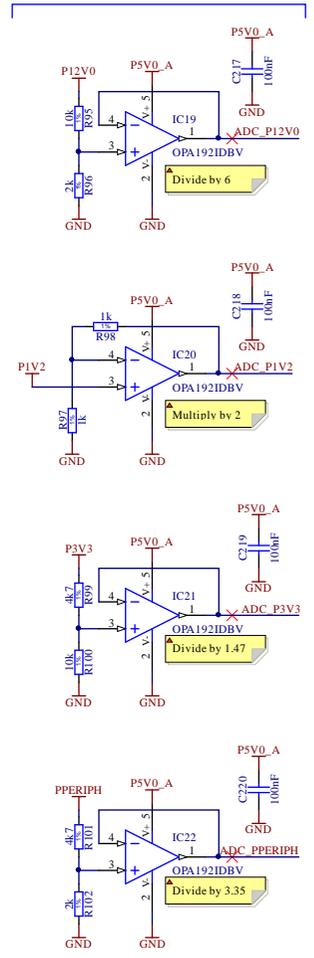
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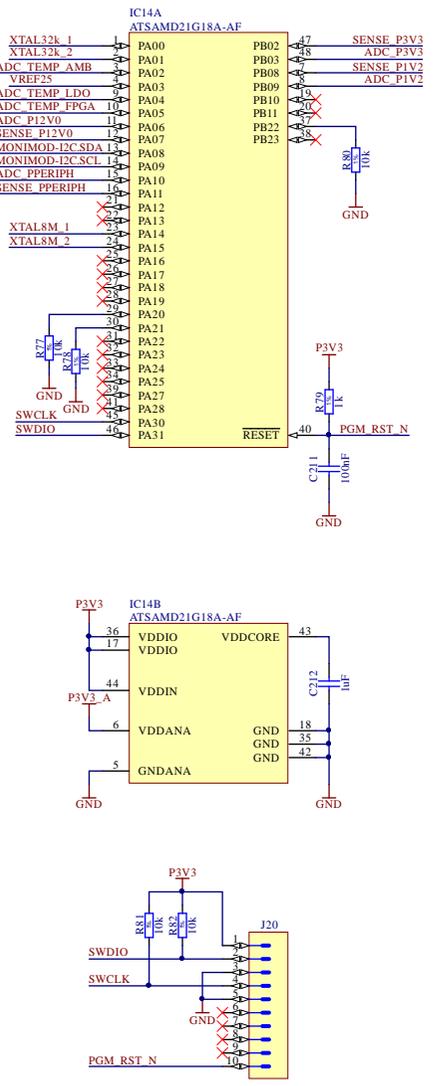
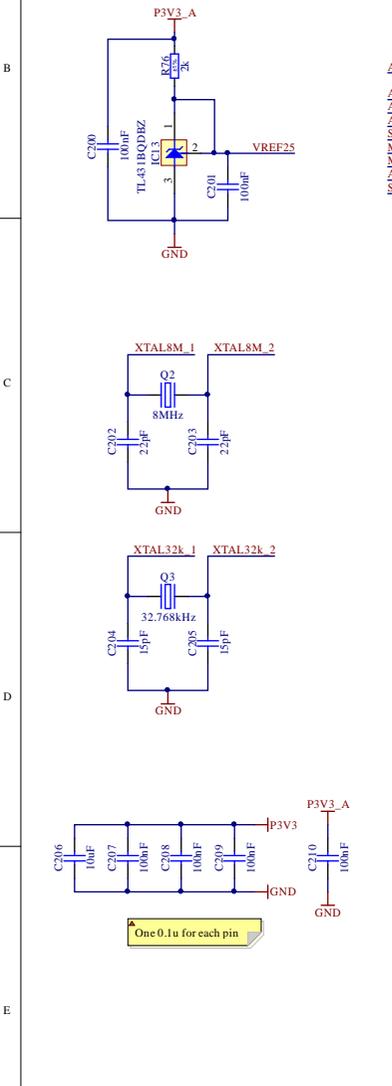
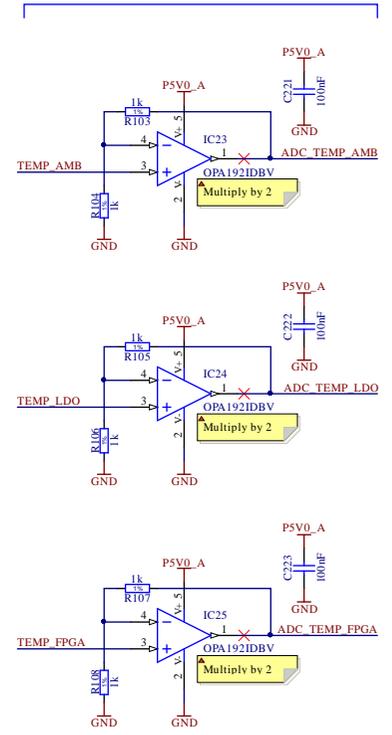
Current sense



Voltage div. and buffers



Temp. sensor amps



Project/Equipment		DI/OT	
Document	Designer		C. Gentsos
	Drawn by		C. Gentsos
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	File		Monitoring_SchDoc
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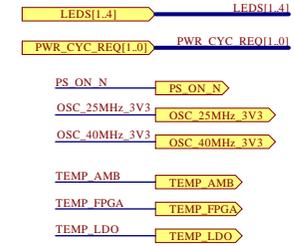
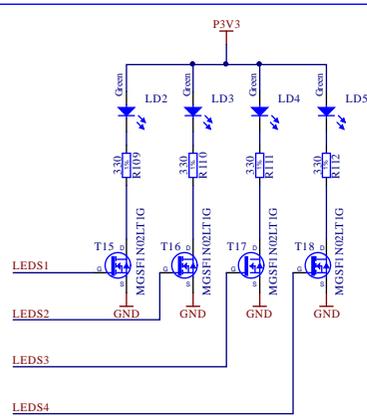
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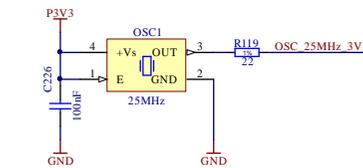
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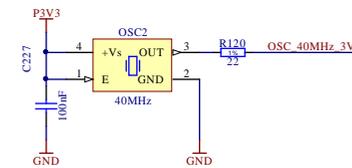
User LEDs



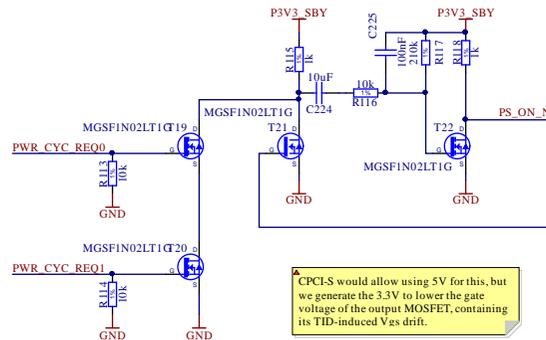
25MHz oscillator



40MHz oscillator

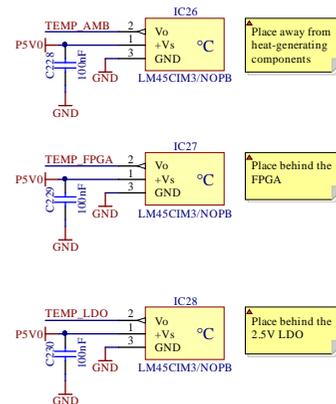


Power cycle pulse generator



▲ CPCL-S would allow using 5V for this, but we generate the 3.3V to lower the gate voltage of the output MOSFET, containing its TID-induced Vgs drift.

Temp sensors

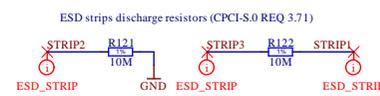


▲ Place away from heat-generating components

▲ Place behind the FPGA

▲ Place behind the 2.5V LDO

ESD Protection



ESD strips discharge resistors (CPCL-S.0 REQ 3.71)

ESD_STRIP, ESD_STRIP, ESD_STRIP

Project/Equipment	DI/OT	Designer	C. Gentsos
Document	DI/OT Rad-tol System Board	Drawn by	C. Gentsos
	Miscellaneous	Check by	*
		Last Mod.	C. Gentsos
		File	Top_Misc.SchDoc
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